

What is claimed is:

- Sub a¹ →
1. A tape carrier type semiconductor device comprising:
 - a flexible substrate on whose surface wiring is formed; and
 - a driver circuit which is mounted on said flexible substrate and drives a device connected to said flexible substrate, and
 - 5 wherein said flexible substrate includes a first slit having a connector for connecting both sides of the first slit.
 2. The tape carrier type semiconductor device according to claim 1, wherein the first slit includes a plurality of connectors.
 3. The tape carrier type semiconductor device according to claim 2, wherein parts of the slit, which are separated from each other at the connector, are diverged from each other at the connector in a direction perpendicular to the slit.
 4. The tape carrier type semiconductor device according to claim 3, wherein said flexible substrate includes a plurality of first slits.
 5. The tape carrier type semiconductor device according to claim 4, wherein said flexible substrate includes a second slit for folding said tape carrier type semiconductor device.
 - Sub a² → 6. The tape carrier type semiconductor device according to claim 5, wherein said flexible substrate includes a rib which is formed substantially perpendicular to the plurality of first slits.
 7. The tape carrier type semiconductor device according to claim 6, a portion of said flexible substrate is changed in shape, thereby to form the rib.
 - Sub a³ → 8. The tape carrier type semiconductor device according to claim 1, wherein said flexible substrate includes a rib which is formed substantially perpendicular to the first slit.
 9. The tape carrier type semiconductor device according to claim 8, wherein a portion of said flexible substrate is changed in shape, thereby to form the rib.

Add a^6